

**AMENDMENTS TO THE SPECIFICATION**

Please amend the title as follows:

**METHOD AND STRUCTURE FOR TEMPORARILY ISOLATING A DIE FROM  
A COMMON CONDUCTOR TO FACILITATE WAFER LEVEL TESTING**

Please substitute paragraph 7 beginning on page 3 with the following:

The present invention provides ~~a method and an~~ apparatus which facilitates temporary isolation of a die from one or more common conductors during wafer level testing. The one or more common conductors extend over a wafer and are connected to a plurality of dice on the wafers which are undergoing testing. A temporary isolation device (e.g., a diode, transistor or other element) is interposed between each die and the common conductor. The temporary isolation device can be used to isolate a die from the common conductor during wafer level testing whenever such isolation is needed.

Please amend the abstract as follows:

The invention provides ~~a method and~~ an apparatus for temporarily isolating a die from other dice on a wafer commonly connected to one or more common conductors. The conductors are connected to each die through a temporary isolation device, such as a diode. The common conductor supplies a signal to all dice during one set of test procedures, while the temporary isolation device can be used to isolate a die from the common conductor during another set of test procedures.

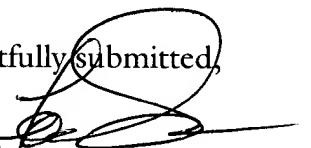
REMARKS

The title, summary of the invention and the abstract of the Specification have been amended to remove reference to a method. This amendment is necessitated due to the previous election of claims in response to a restriction requirement. After the restriction requirement response, the application no longer contained method claims. Accordingly, the title, summary and abstract are being amended to better conform to the claimed invention.

In view of the above, Applicant respectfully requests entry of the above amendments prior to issuance of the Application.

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Respectfully submitted,

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